

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00582	1.27	0.06223
	Doped silicon	Silicon (Si)	7440-21-3	0.45247	98.73	4.83777
<b>Subtotal</b>				<b>0.45829</b>	<b>100</b>	<b>4.9</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0375	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01125	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.0375	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.41842	99.77	400.0777
<b>Subtotal</b>				<b>37.50467</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84175	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.92031	10.0	63.3
	Filler	Silica fused	60676-86-0	50.32267	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11841	0.2	1.266
<b>Subtotal</b>				<b>59.20314</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.3382	100.0	25
<b>Subtotal</b>				<b>2.3382</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.16835	100.0	1.8
<b>Subtotal</b>				<b>0.16835</b>	<b>100</b>	<b>1.8</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00655	2.0	0.07
	Lead alloy	Silver (Ag)	7440-22-4	0.00818	2.5	0.0875
	Lead alloy	Lead (Pb)	7439-92-1	0.31262	95.5	3.3425
<b>Subtotal</b>				<b>0.32735</b>	<b>100</b>	<b>3.5</b>
<b>Total</b>				<b>100</b>	<b>100</b>	<b>1069.2</b>

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